

25A, 45V Dual Common Cathode Schottky Rectifier

FEATURES

- Low power loss, high efficiency
- Ideal for automated placement
- Guardring for overvoltage protection
- High surge current capability
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

MECHANICAL DATA

Case: TO-263AB (D²PAK)

Molding compound, UL flammability classification rating 94V-0 Moisture sensitivity level: level 1, per J-STD-020 Part no. with suffix "H" means AEC-Q101 qualified Packing code with suffix "G" means green compound (halogen-free) **Terminal:** Matte tin plated leads, solderable per JESD22-B102 Meet JESD 201 class 2 whisker test **Polarity:** As marked **Weight:** 1.4 g (approximately)



TO-263AB (D²PAK)

Κ

--O HEATSINK

PIN 10-

PIN 2 O





PARAMETER	SYMBOL	MBRS25H45CT	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	45	V
Maximum RMS voltage	V _{RMS}	31	V
Maximum DC blocking voltage	V _{DC}	45	V
Maximum average forward rectified current	I _{F(AV)}	25	A
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	150	А
Maximum instantaneous forward voltage (Note 1) I _F =12.5A, T _J =25°C I _F =12.5A, T _J =125°C I _F =25A, T _J =25°C I _F =25A, T _J =125°C	V _F	0.70 0.60 0.90 0.75	V
Maximum reverse current @ rated V_R T _J =25°C T _J =125°C	I _R	0.2 15	mA
Voltage rate of change (Rated V _R)	dV/dt	10000	V/µs
Typical thermal resistance	R _{θJC} R _{θJA}	1.5 50	°C/W
Operating junction temperature range	TJ	- 55 to +175	°C
Storage temperature range	T _{STG}	- 55 to +175	°C

Note 1: Pulse test with PW=300µs, 1% duty cycle



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ORDERING INFORMATION					
PART NO.	PART NO.	PACKING CODE	PACKING CODE	PACKAGE	PACKING
	SUFFIX		SUFFIX ^(*)		
MBRS25H45CT	Ц	RN	G	D ² PAK	800 / 13" Paper reel
	11	MN			800 / 13" Plastic reel

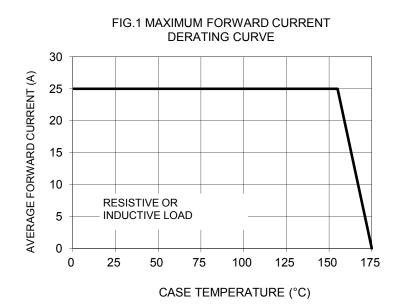
*: Optional available

EXAMPLE					
PREFERRED P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
MBRS25H45CTHRNG	MBRS25H45CT	Н	RN	G	AEC-Q101 qualified Green compound

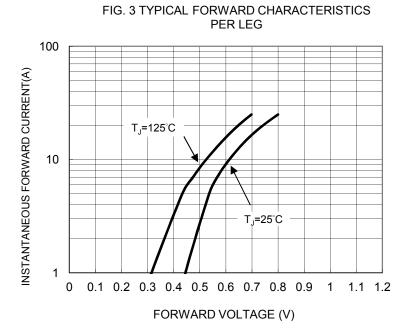
150

RATINGS AND CHARACTERISTICS CURVES

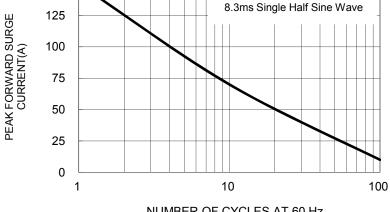
(T_A=25°C unless otherwise noted)



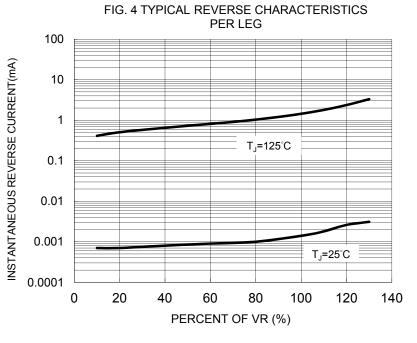






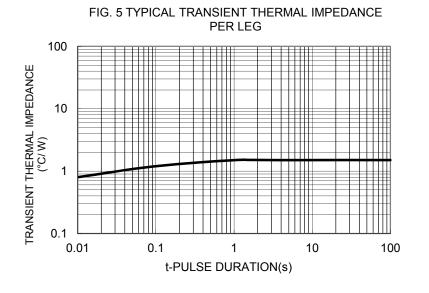


NUMBER OF CYCLES AT 60 Hz

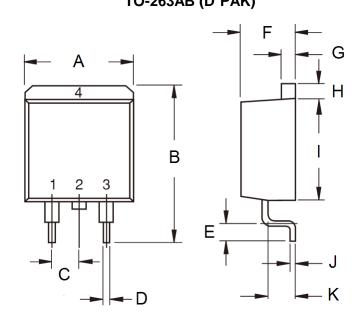




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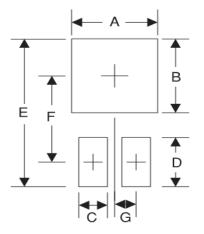


PACKAGE OUTLINE DIMENSIONS TO-263AB (D²PAK)



DIM.	Unit	(mm)	Unit (inch)		
Dilvi.	Min	Max	Min	Max	
Α	-	10.5	-	0.413	
В	14.60	15.88	0.575	0.625	
С	2.41	2.67	0.095	0.105	
D	0.68	0.94	0.027	0.037	
E	2.29	2.79	0.090	0.110	
F	4.44	4.70	0.175	0.185	
G	1.14	1.40	0.045	0.055	
Н	1.14	1.40	0.045	0.055	
I	8.25	9.25	0.325	0.364	
J	0.36	0.53	0.014	0.021	
К	2.03	2.79	0.080	0.110	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	10.8	0.425
В	8.3	0.327
С	1.1	0.043
D	3.5	0.138
E	16.9	0.665
F	9.5	0.374
G	2.5	0.098

MARKING DIAGRAM



- = Specific Device Code
- = Green Compound
- = Date Code
- = Factory Code



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